



2827

MAS-FIN-153

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450:

By: 

Date: January 30, 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No. : 10/090,289 Confirmation No. 6619  
Applicant : Johann Winderl  
Filed : March 4, 2002  
TC/A.U. : 2827  
Examiner : Luan C. Thai  
Title : Electronic Component with Stacked  
Semiconductor Chips

Docket No. : MAS-FIN-153  
Customer No. : 24131

Hon. Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

RECEIVED  
JAN - 5 2005  
TECHNOLOGY CENTER 2800

**AMENDMENT**

S i r :

In response to the Office action dated January 6, 2004, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 8 of this paper.

